REFURBISHED STEPPER

Thin Film Head and Air Bearing Surfaces

The Model 1700MVS is one of Ultratech's most sophisticated tools being used today in the industry for air bearing surface patterning applications. Incorporating an advanced machine vision system and customized software specifically designed for rowbar level processing, the 1700MVS recognizes and automatically aligns to preexisting features, thus eliminating the need for special targets

The model 1700MVS is the world's most widely used thin film head (TFH) lithography tool for high-volume manufacturing. Design simplicity makes the 1700MVS a highly reliable, easy-to-operate, and easy-to-maintain system. Its low initial investment cost and low operating costs also enable it to provide tremendous cost-of-ownership benefits.

The UltraStep 1700MVS features include:

* *1.4um, 1.2, or 1.0um resolution*
* *Machine Vision Alignment*
* *3 x 5 x 0.09 or 5 x 5 x 0.90 inch reticle*
* *Air probe focus detection*
* *Automatic site-by-site alignment*
* *Manual substrate thickness compensator*
* *Broadband exposure (g/h -line)*
* *Flexible field size (34.2 x 13.6 mm)*
* *High wafer plane irradiance*
* *Large depth of focus*
* *Multiple fields per reticle*

SPECIFICATIONS:

Wafer Size:	3”, 4”, 5”, 6”, or 8”
Loader Type:	Automation / Manual
Computer:	HP 362 w/Hard Disk
Machine Vision:	Cognex
Uniformity:	3.0 %
Depth of Focus:	4.0 ums @ 1.2um lines
	7.0 ums @ 1.4um lines
Maximum Square:	18 x 18 mm
Maximum Aspect:	39 x 11.4 mm
Maximum Area:	34.2 x 13.6 mm
Reticle Size:	3” x 5” x 0.090”

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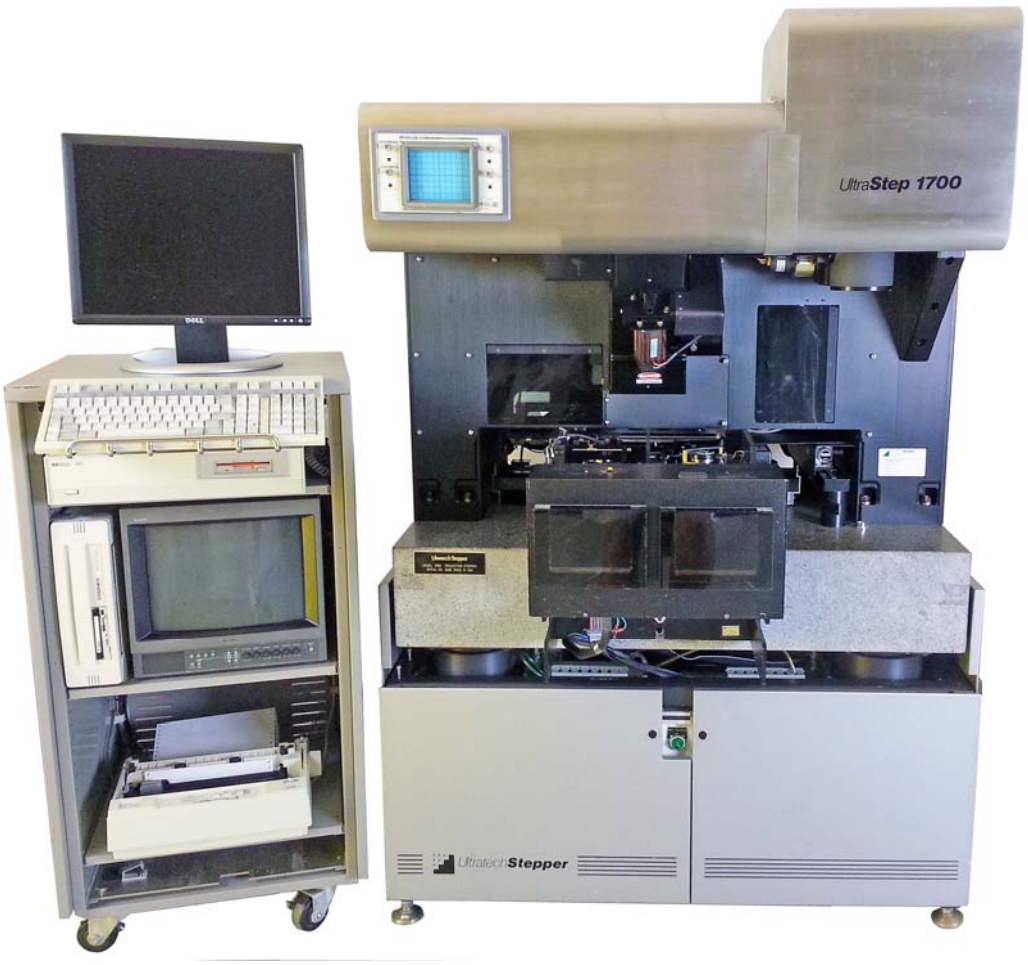
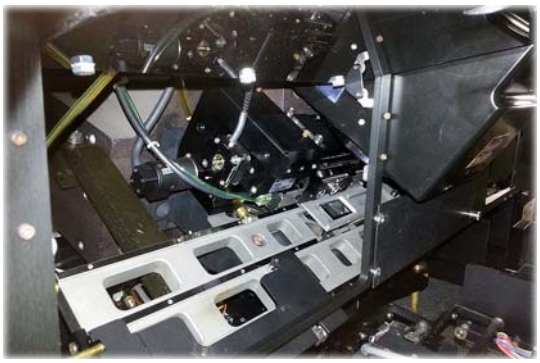
Ultratech Model 1700 MVS Machine Vision System

Serial Number 1239
Manufactured September, 1996
Minimum resolution: 1.2um
Full field or Rowbar Illumination



Machine Vision Reticle Stage



Manufacturing label